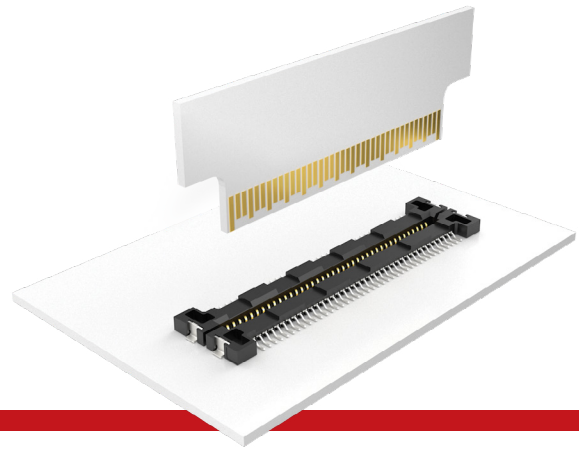


HIGH-SPEED THROUGH BOARD SOCKET

(1.00 mm) .0394" PITCH • SAL1 SERIES

14
G b p s



SAL1

Card Mates:

(1.60 mm) .062" or
(2.36 mm) .093" card

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over 50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

2.9 A per pin
(2 adjacent pins powered)

Voltage Rating:

215 VAC/304 VDC

PROCESSING

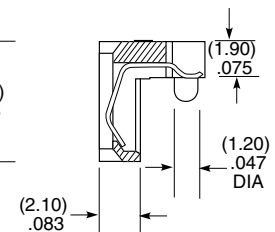
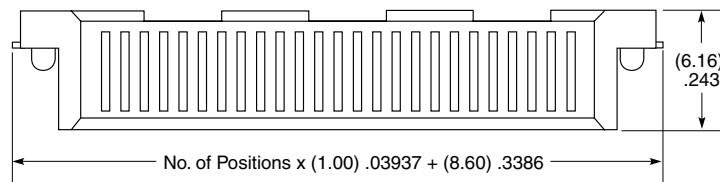
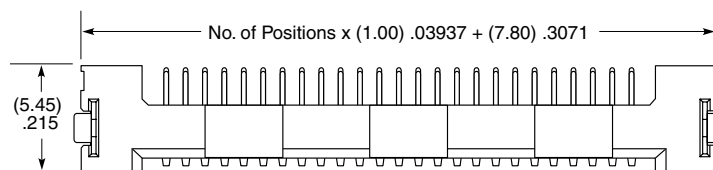
Lead-Free Solderable:

Yes

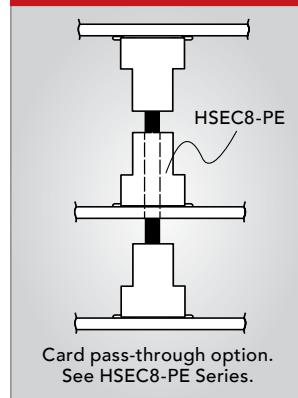
SMT Lead Coplanarity:

(0.10 mm) .004" max

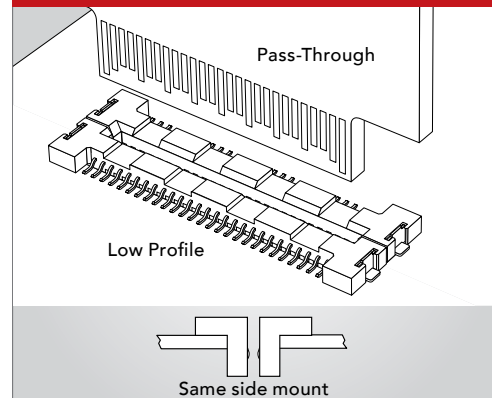
SAL1	-	1	NO. OF POSITIONS	-	01	PLATING OPTION	-	S	-	A	-	OPTION
			-20, -27, -30, -40			-S = 30 μ " (0.76 μ m) Gold on contact, Matte tin on tail						-TR = Tape & Reel -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)



OTHER SOLUTION



APPLICATIONS



Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications..

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?SAL1

samtec.com/EdgeCard

F-224 (Rev 09DEC24) WEB

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.